Kingbright

58.34mm (2.3 INCH) 8x8 DOT MATRIX DISPLAY

Part Number: TC23-11SEKWA

Super Bright Orange

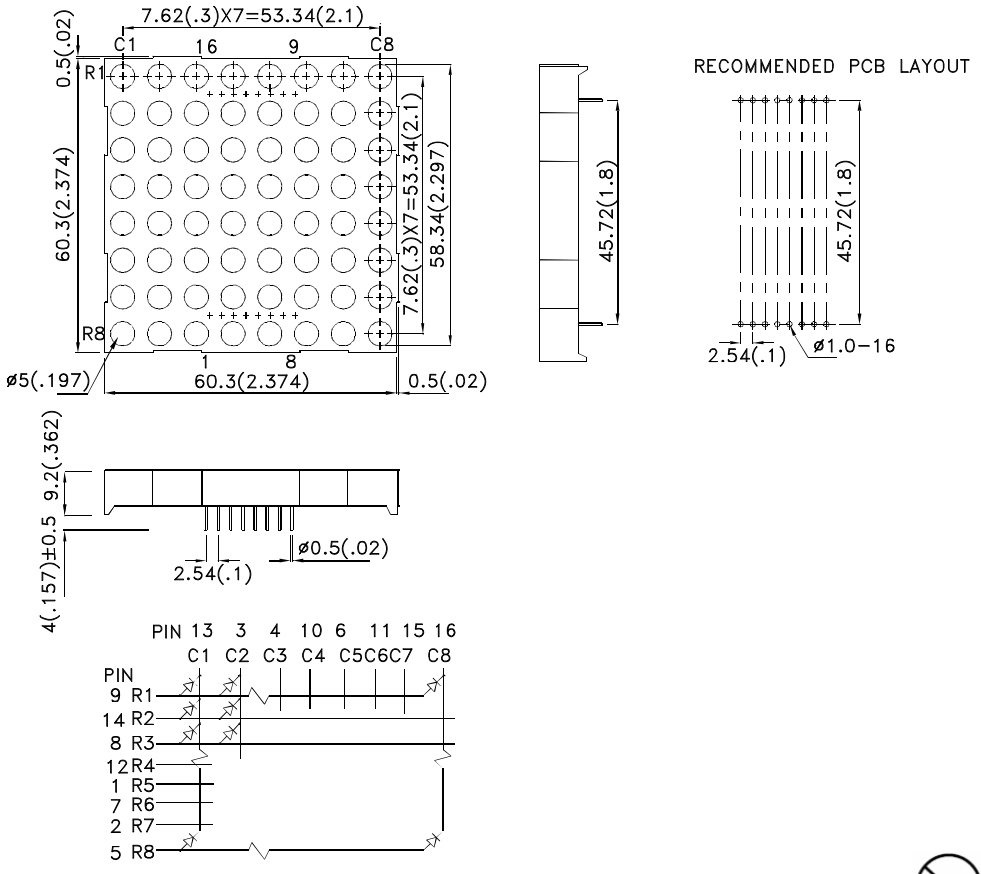
Features

- 2.3 inch matrix height.
- Dot size 5mm.
- Low current operation.
- High contrast and light output.
- Stackable horizontally.
- Column cathode and column anode available.
- Easy mounting on P.C. boards or sockets.
- Multicolor available.
- Mechanically rugged.
- Standard : gray face, white dot.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions& Internal Circuit Diagram



Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
TC23-11SEKWA	Super Bright Orange (AlGaInP)	White Diffused	88000	270000	Column Cathode

Note:
1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25℃

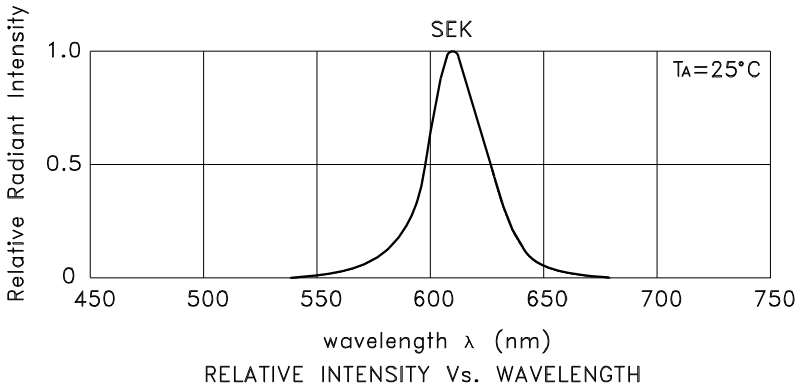
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	I_F=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	I_F=20mA
C	Capacitance	Super Bright Orange	15		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Super Bright Orange		10	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25℃

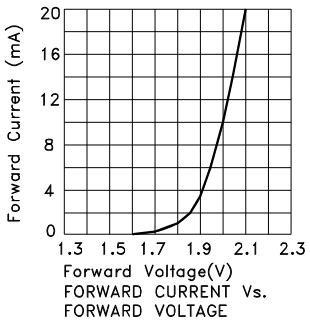
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

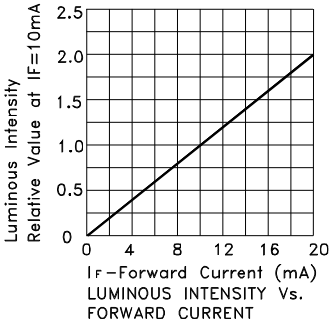


RELATIVE INTENSITY Vs. WAVELENGTH

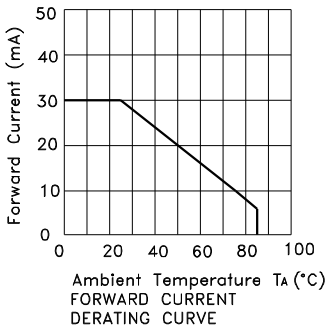
Super Bright Orange **TC23-11SEKWA**



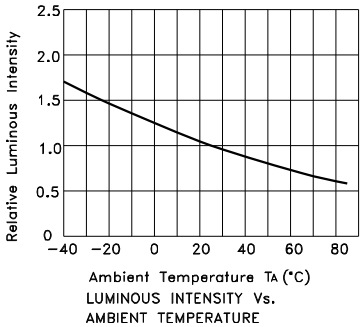
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

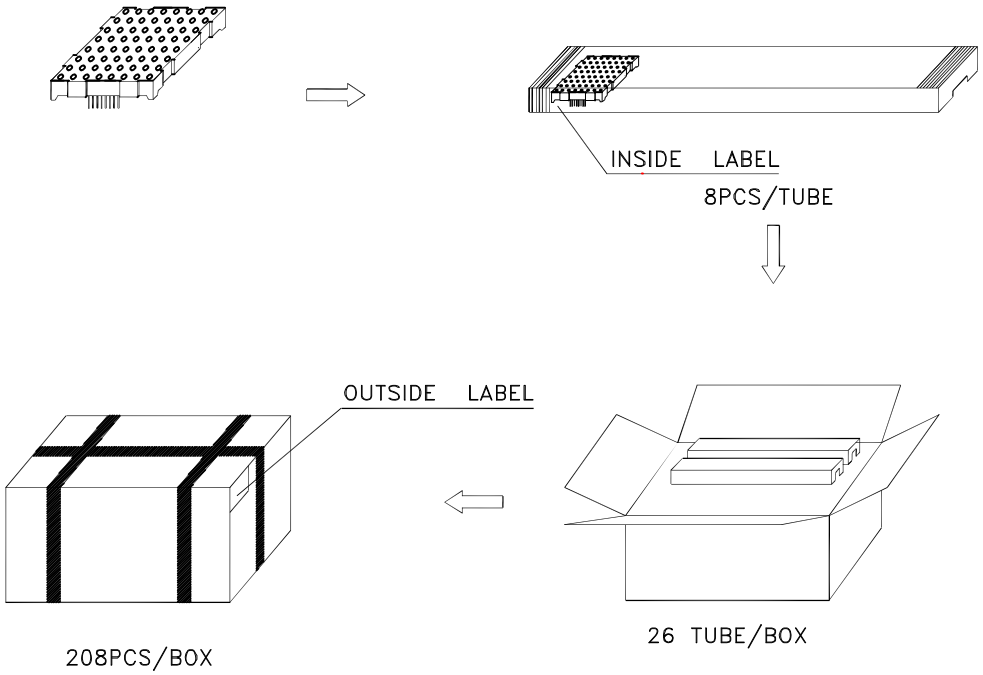


FORWARD CURRENT
DERATING CURVE

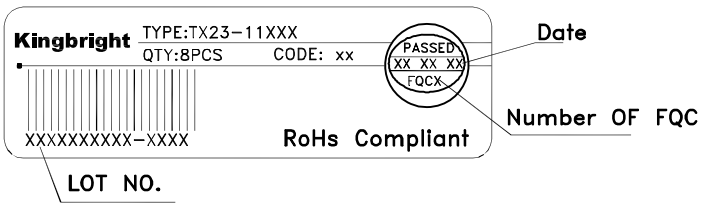


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

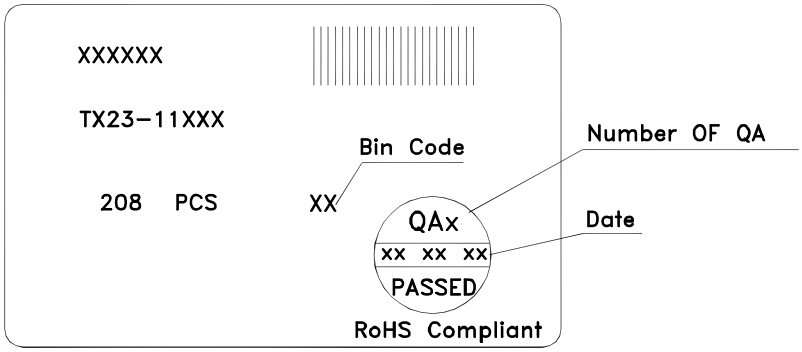
PACKING & LABEL SPECIFICATIONS **TC23-11SEKWA**



Inside Label On IC-tube



Outside Label On Box

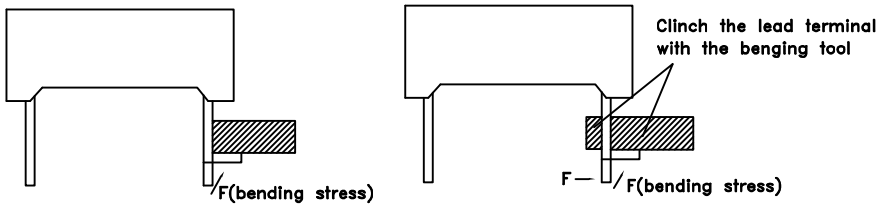


THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.

The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Not Recommended Recommended

Installation

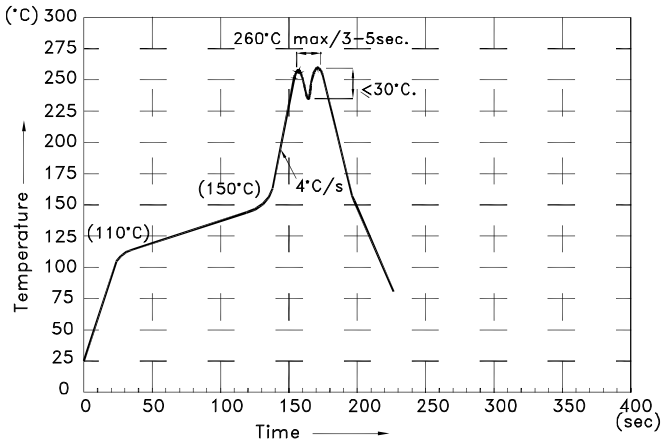
1.The installation process should not apply stress to the lead terminals.

2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

Not Recommended Recommended

DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.

2.Do not apply stress on epoxy resins when temperature is over 85°C.

3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).

4.During wave soldering , the PCB top-surface temperature should be kept below 105°C

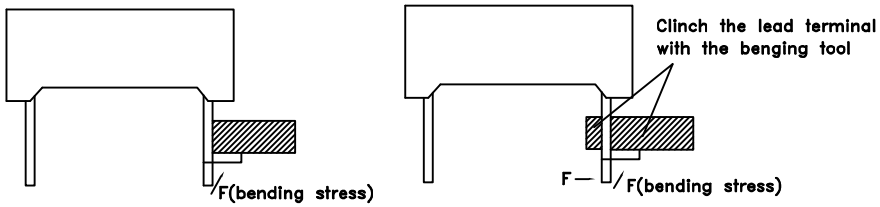
5.No more than once.

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.

The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Not Recommended Recommended

Installation

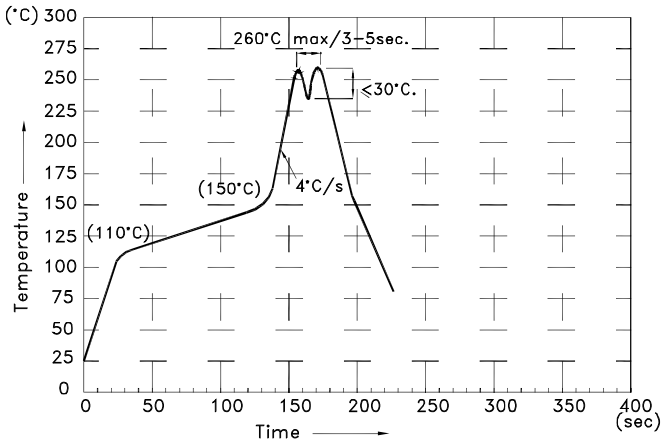
1.The installation process should not apply stress to the lead terminals.

2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

Not Recommended Recommended

DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.

2.Do not apply stress on epoxy resins when temperature is over 85°C.

3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).

4.During wave soldering , the PCB top-surface temperature should be kept below 105°C

5.No more than once.